

CERTIFICATE OF HAND DELIVERY

I hereby certify that this correspondence is being hand filed with the United States Patent and Trademark Office in Washington, D.C. on September 24, 2001.

Melissa Garton
Melissa Garton

179 B
Amult
17 September
10-2-01
AK

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the application of:

Tomohiro HASHII

Serial No.: 09/594,502

Filing Date: June 16, 2000

For: SEMICONDUCTOR WAFER
GRINDING METHOD

Examiner: Robert A. Rose

Group Art Unit: 3723

RECEIVED
OCT - 1 2001
TC 3700 MAIL ROOM

AMENDMENT UNDER 37 CFR 1.111

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated May 24, 2001, Applicants request a 1-Month Extension of Time, as noted in the attached Petition, extending the period for response from August 24, 2001 to September 24, 2001. Please amend this application as follows:

IN THE CLAIMS

Please cancel claims 1-4 without prejudice or disclaimer.

Please add the following new claims:

- B2* *Sub* *cy*
- 5. A method for grinding semiconductor wafers comprising:
grinding a surface of a semiconductor wafer with fixed abrasive grains;